



TITLE: MODIFIED CHIP ATTACH PROCESS AND APPARATUS  
INVENTOR NAME: Sondeep B. Sone et al.  
SERIAL NO.: 10/675,880

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approved  
3/4/05

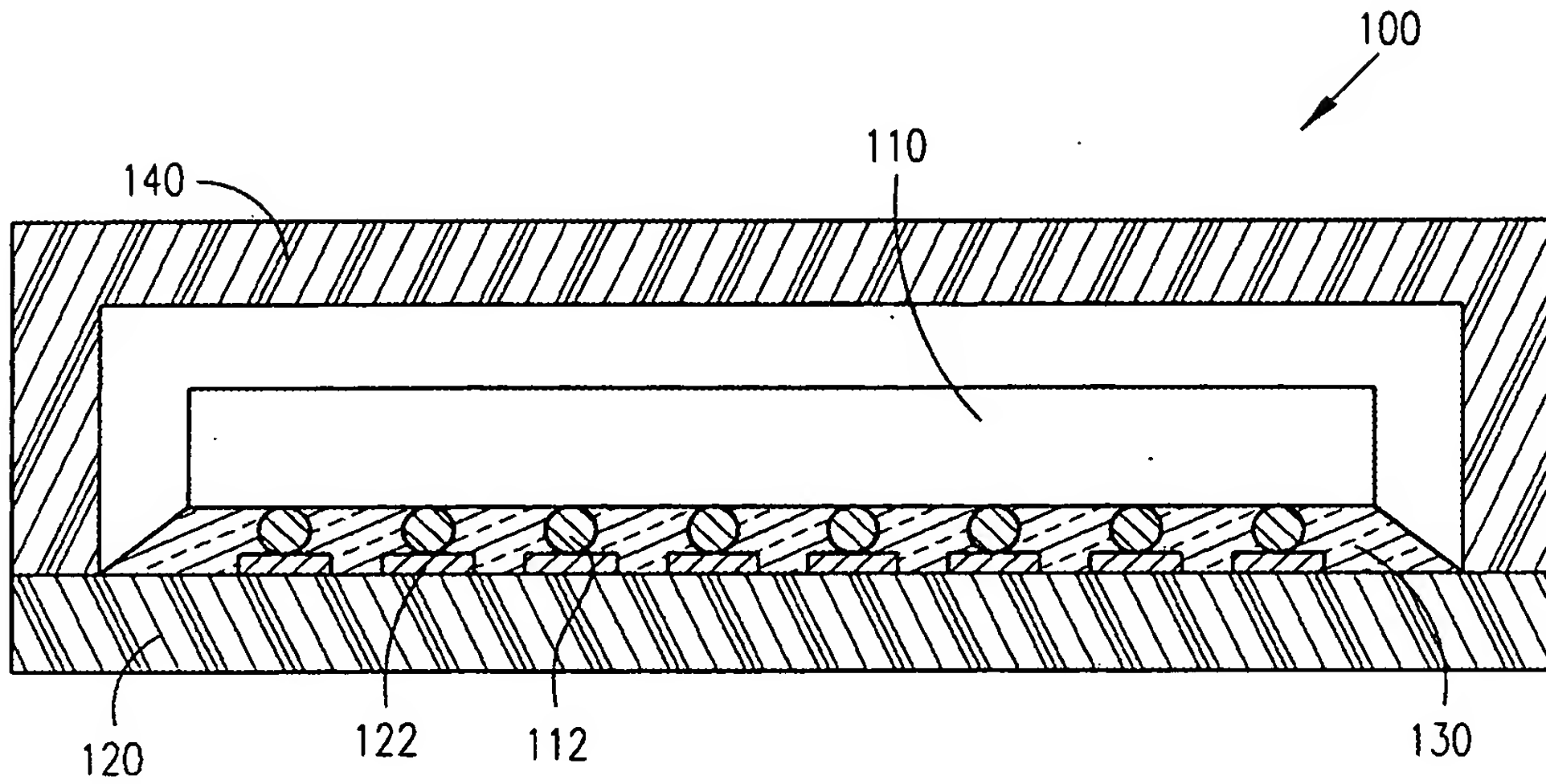


FIG. 1A

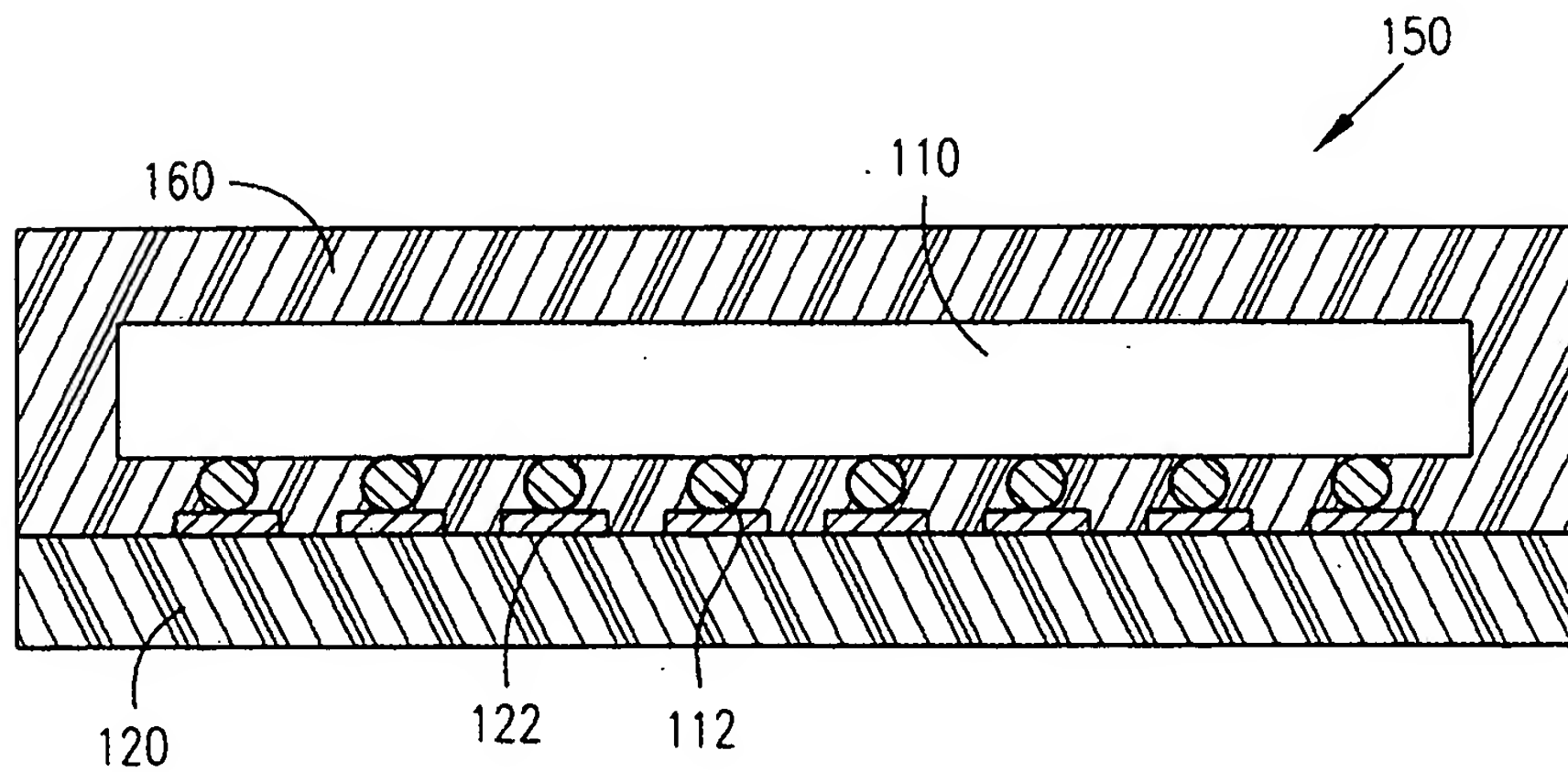


FIG. 1B

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*Handwritten signature*

200  
↓

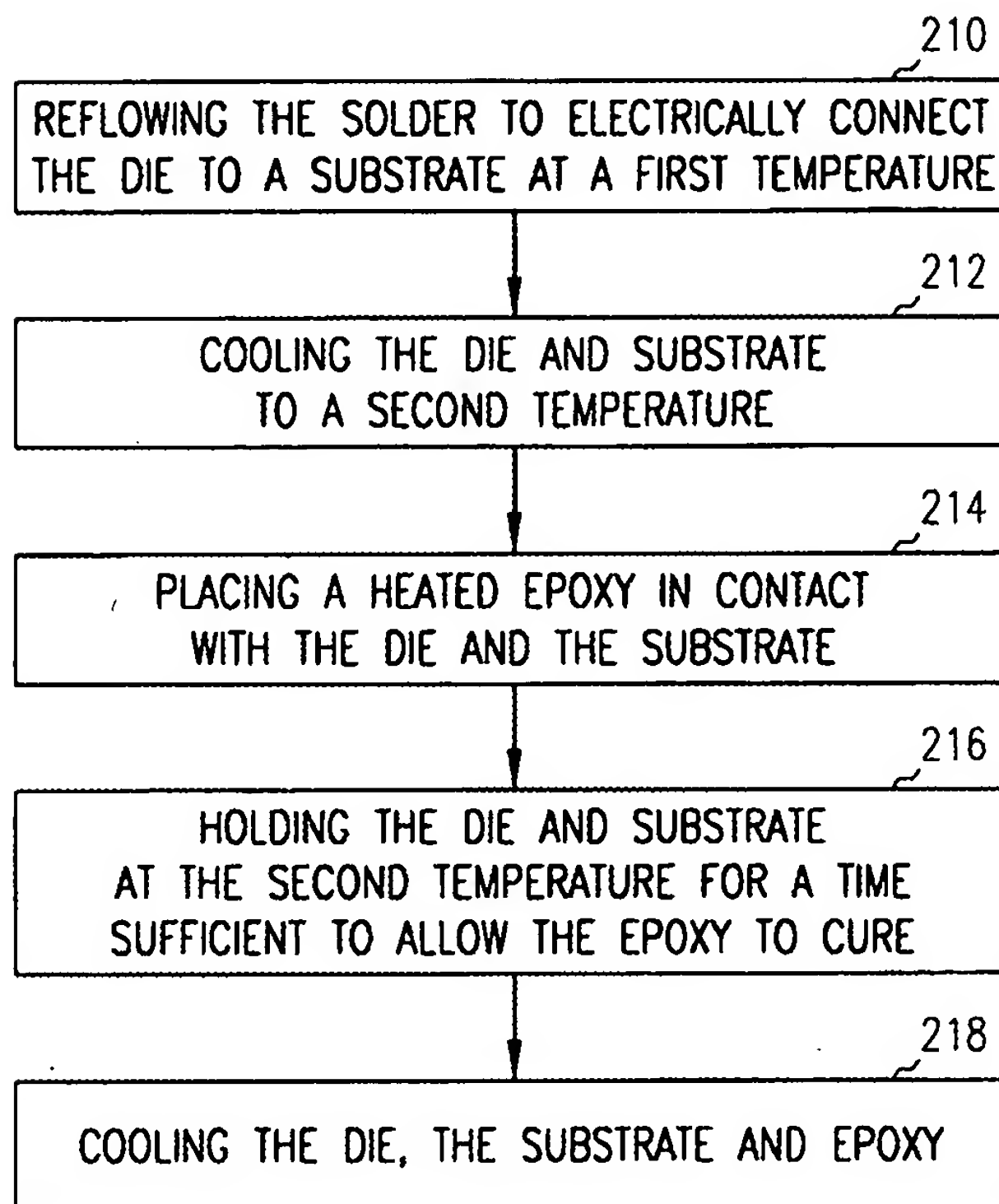


FIG. 2

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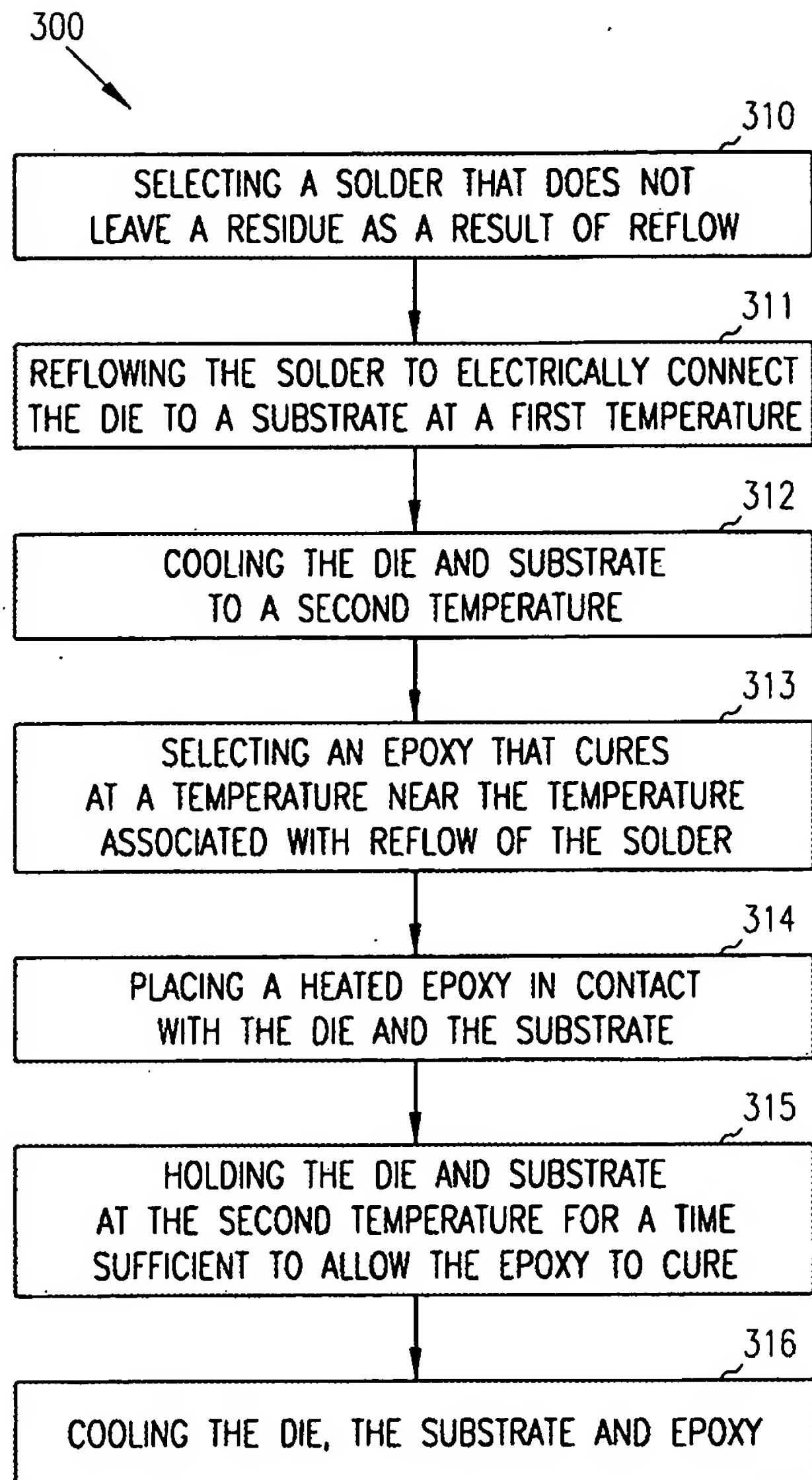


FIG. 3

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Sandeep*

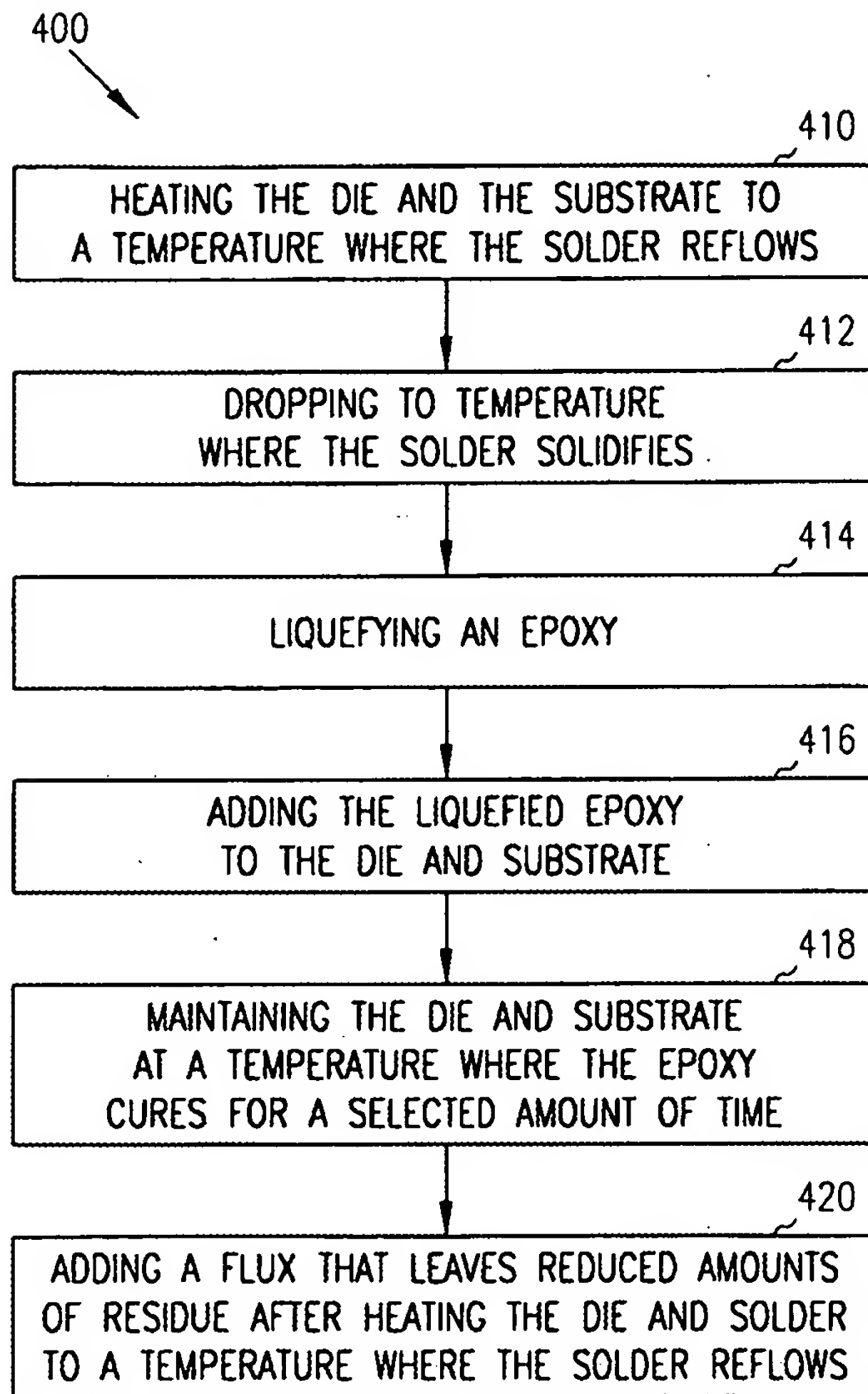


FIG. 4

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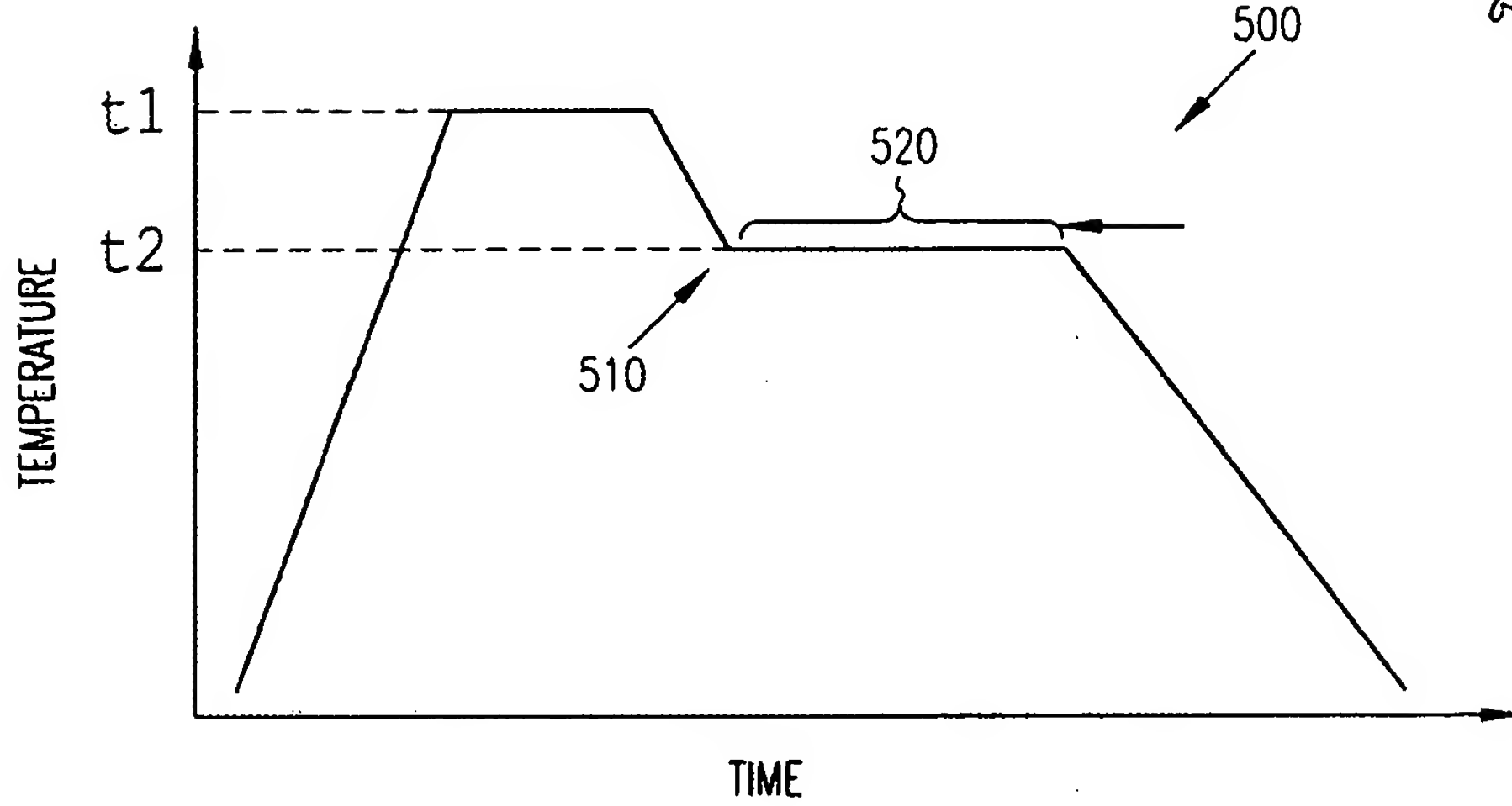


FIG. 5

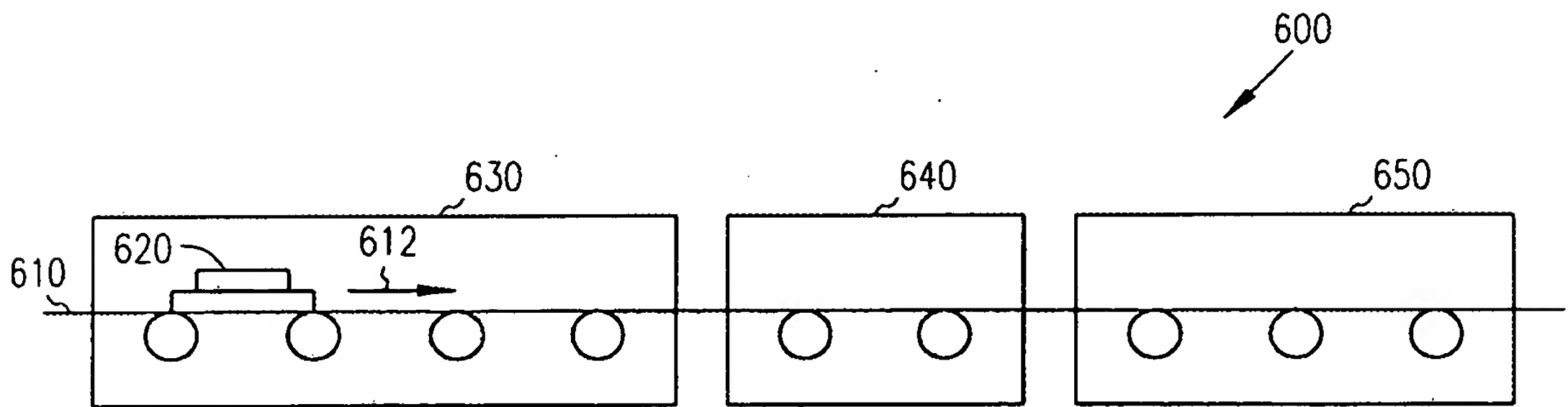


FIG. 6

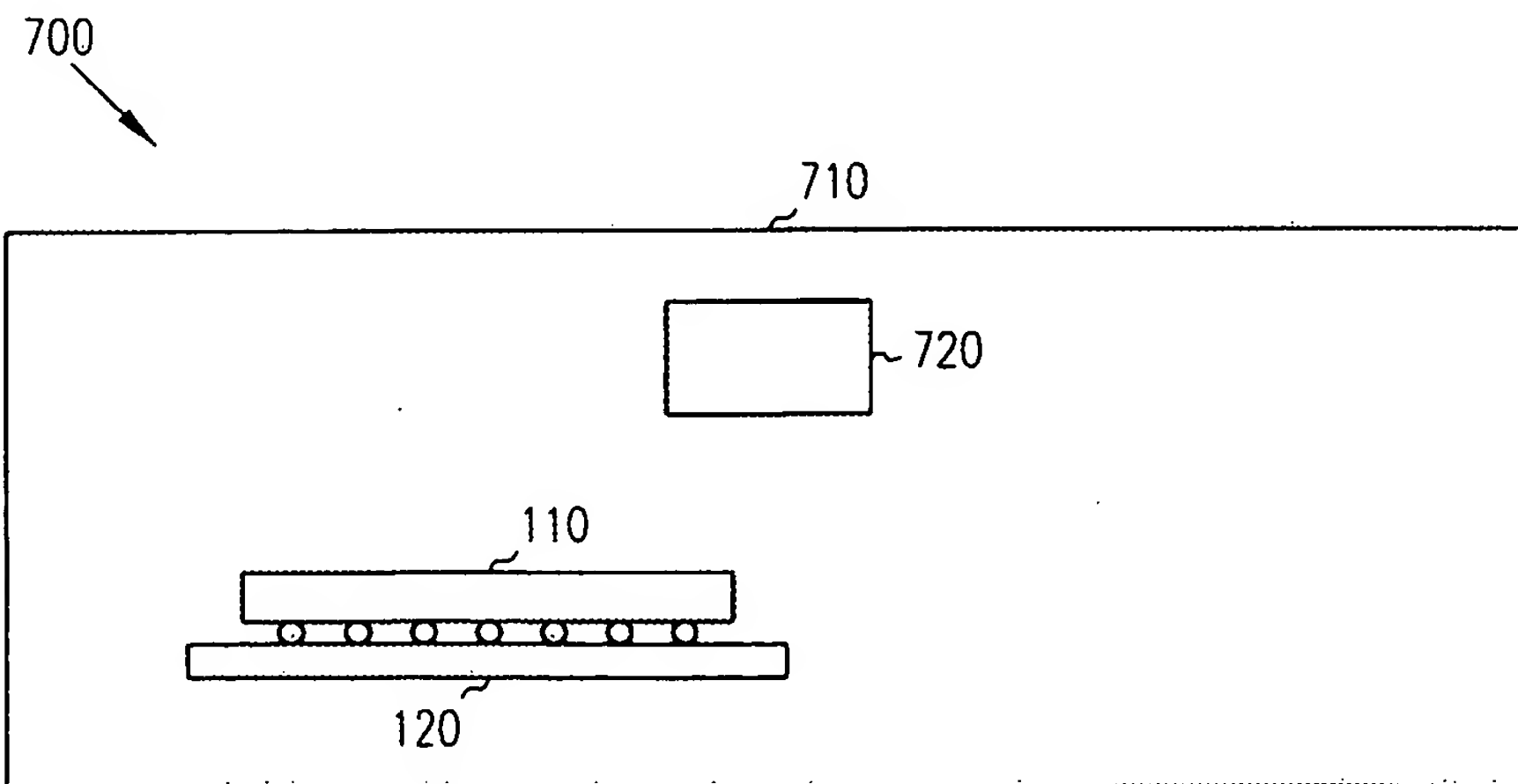


FIG. 7

*Dr  
Sandeep*

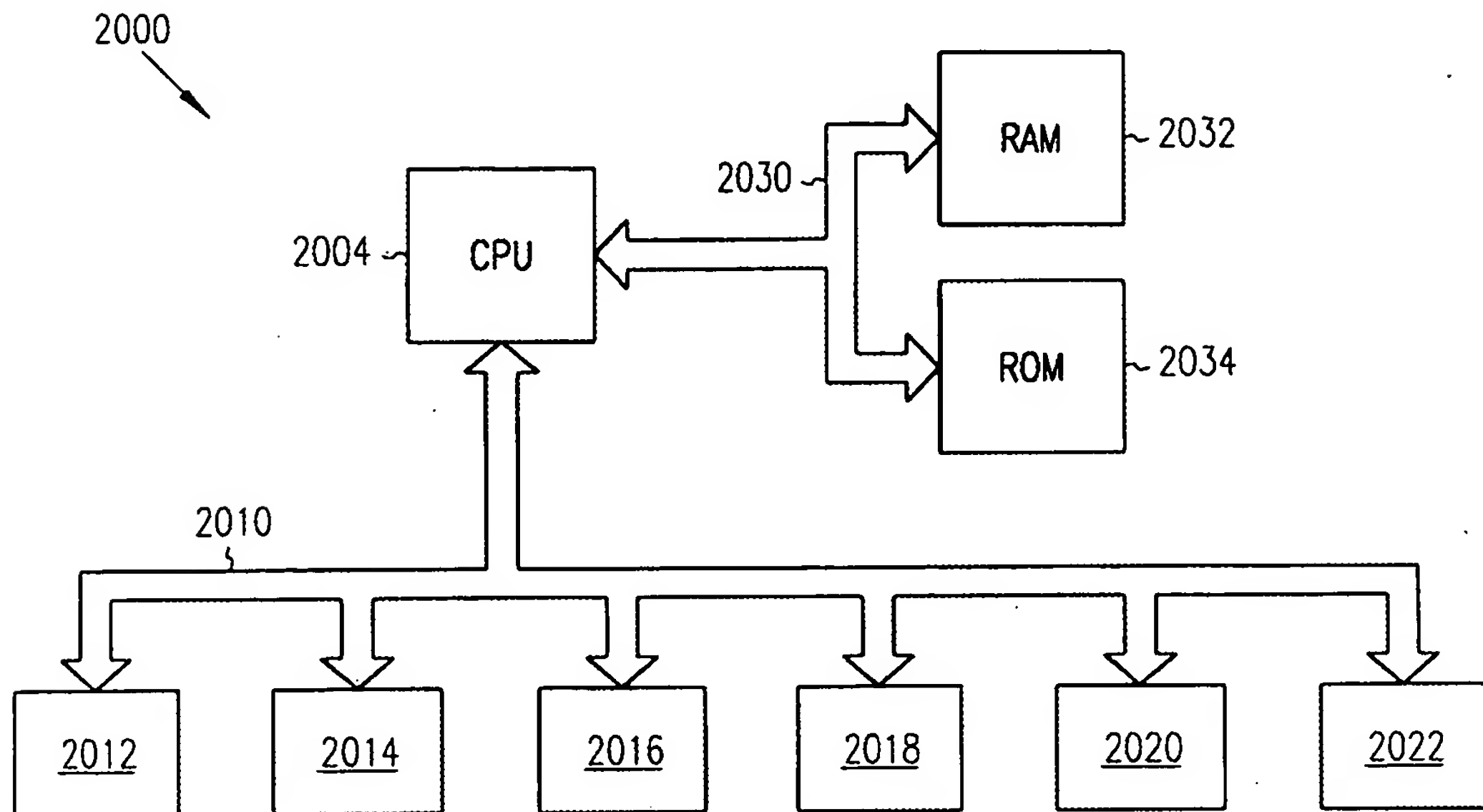


FIG. 8

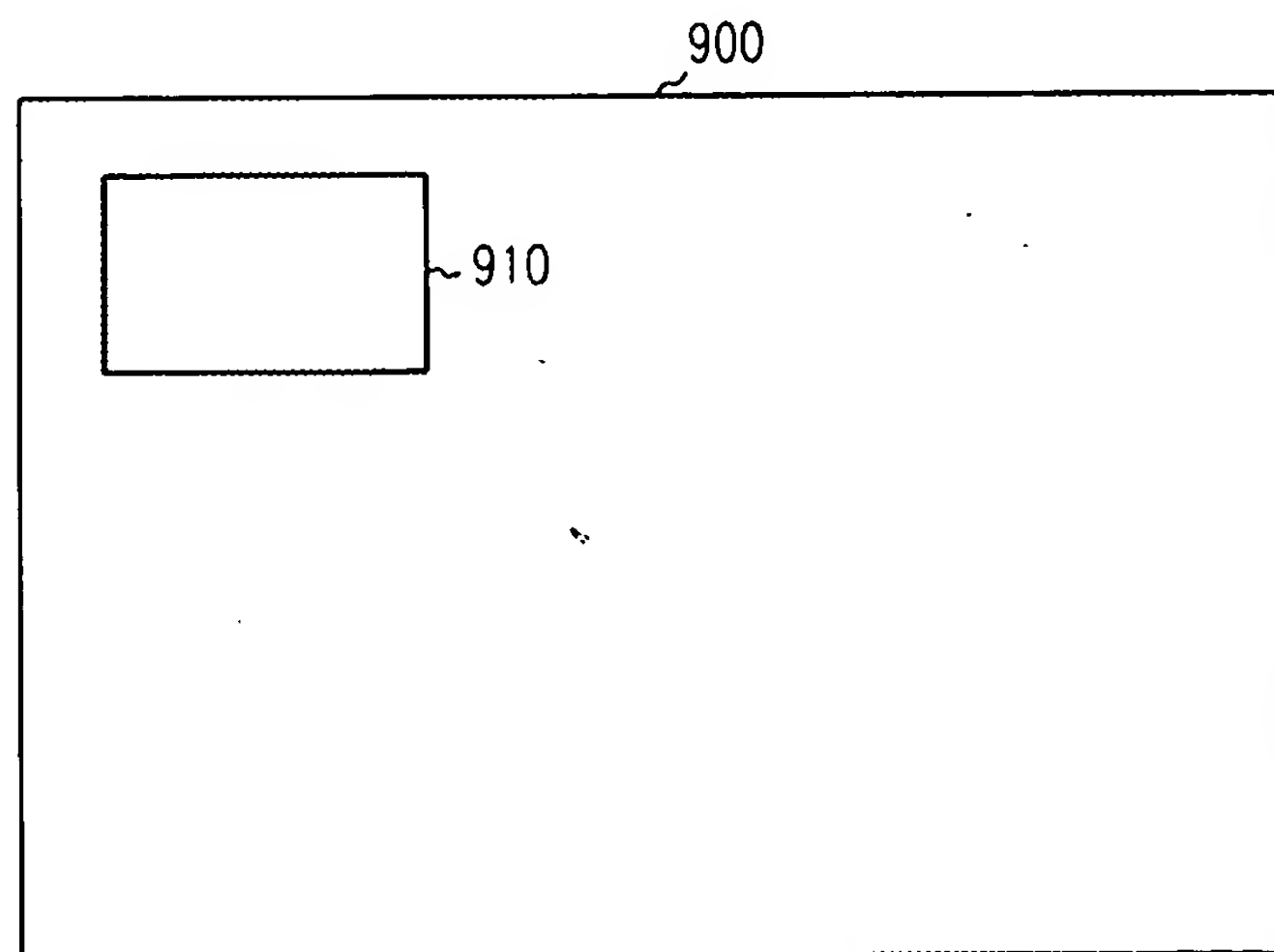


FIG. 9